

Pictures on FE-I4B wafers

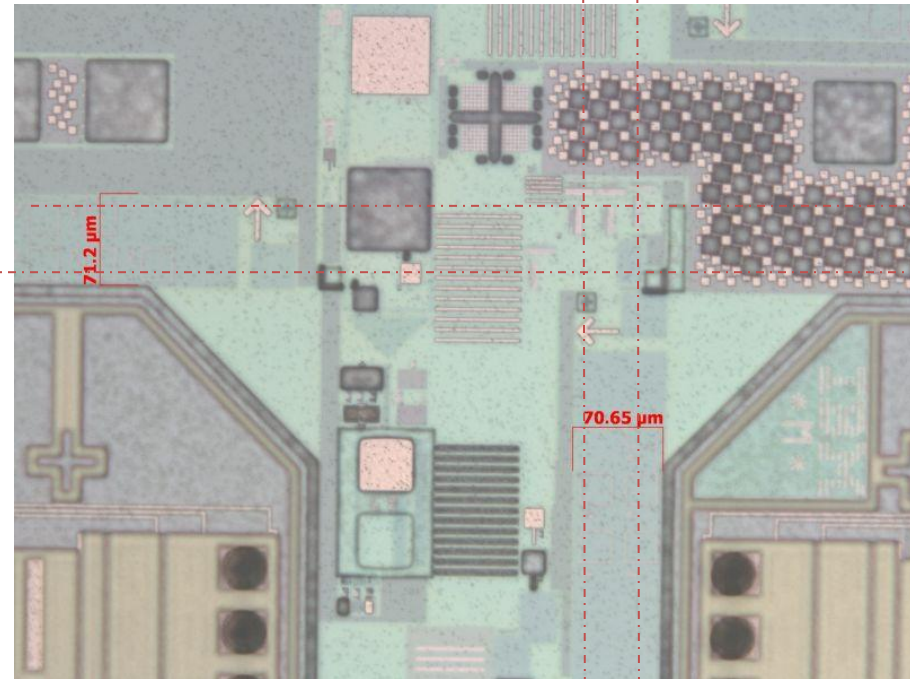
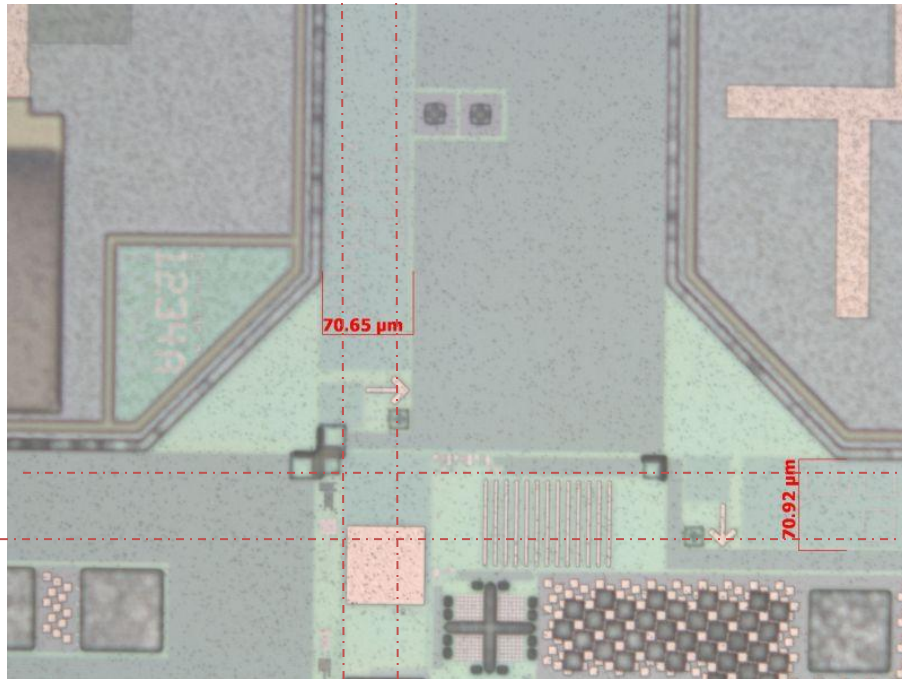
S. Vähänen 23.5.2013 Advacam

Darkened Al Pads on FE-14 ROIC Wafers

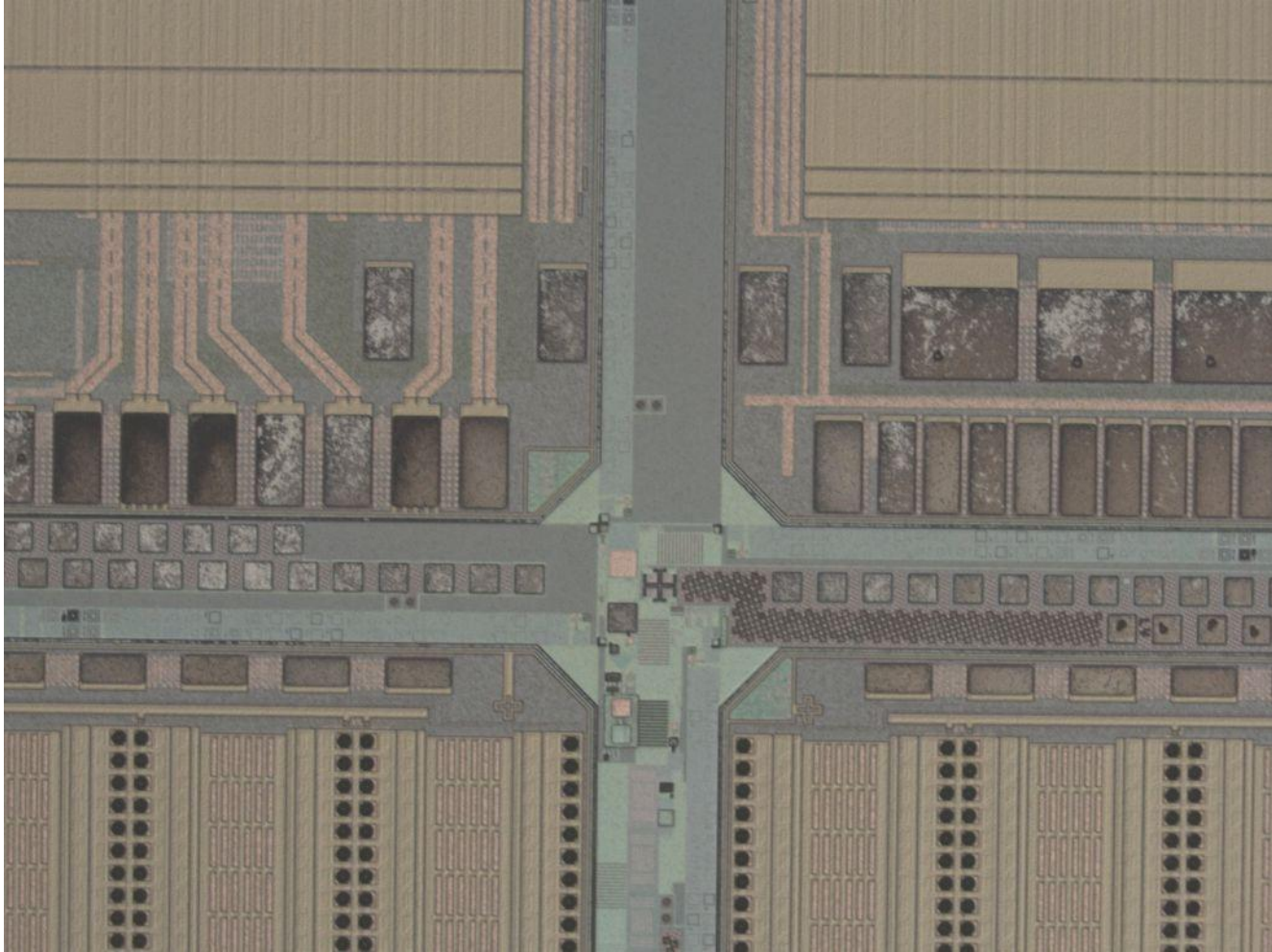
- All the exposed aluminum structures have become dark (rough) during the bumping process
 - Sami's best guess: wet etching chemistry of adhesion layer hasn't been compatible with Al pads
- Effect can be seen all over the wafer
- Wire bondability has been compromised
- Dicing was scheduled for this week
 - What is the next move?

Dicing

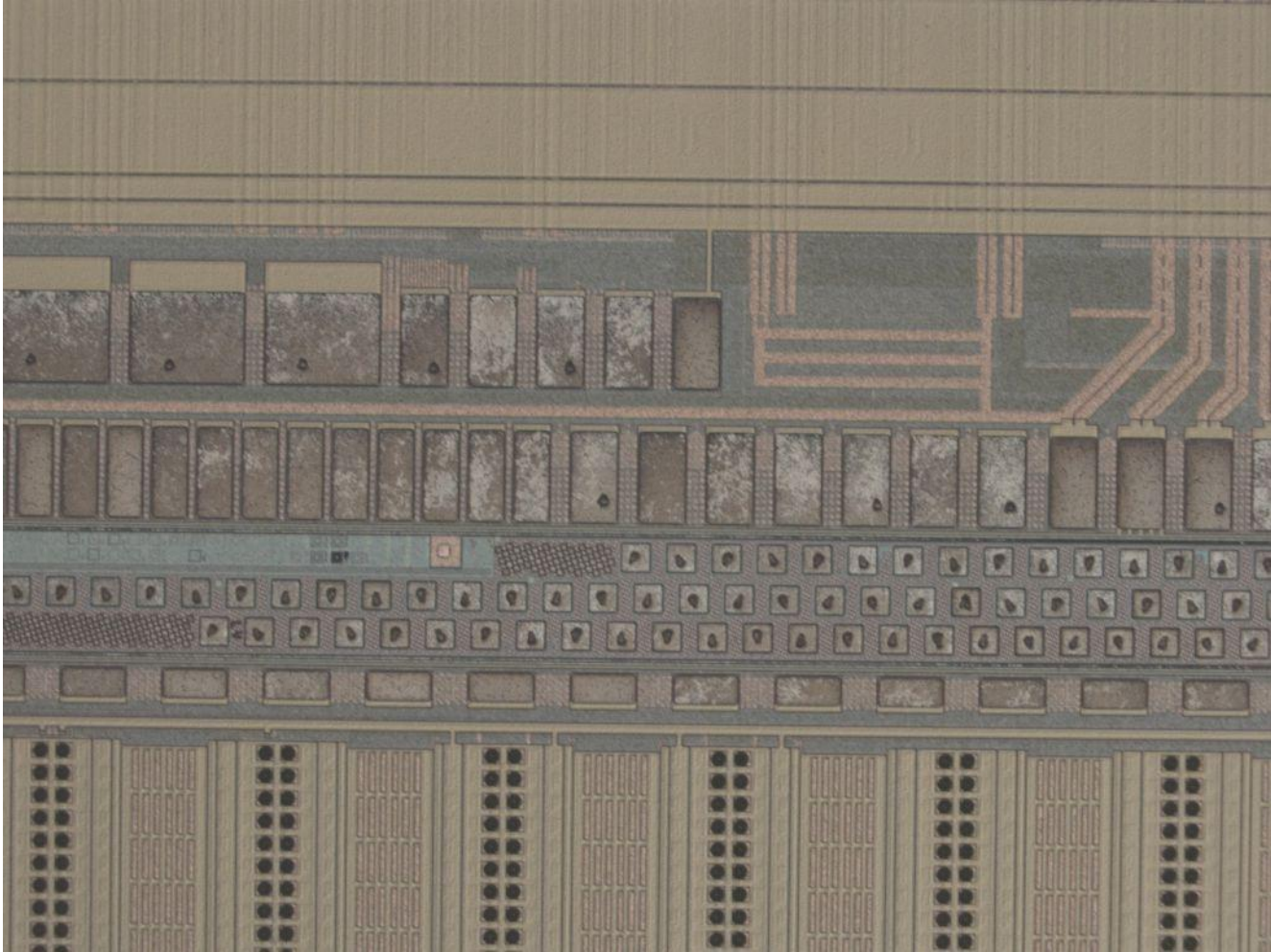
- Sami will dice the wafers as follows:
 - Choice #1: Trench less than $10\ \mu\text{m}$ from the chip frame
 - Choice #2: Trench $40\ \mu\text{m}$ from the chip frame
 - Input needed!



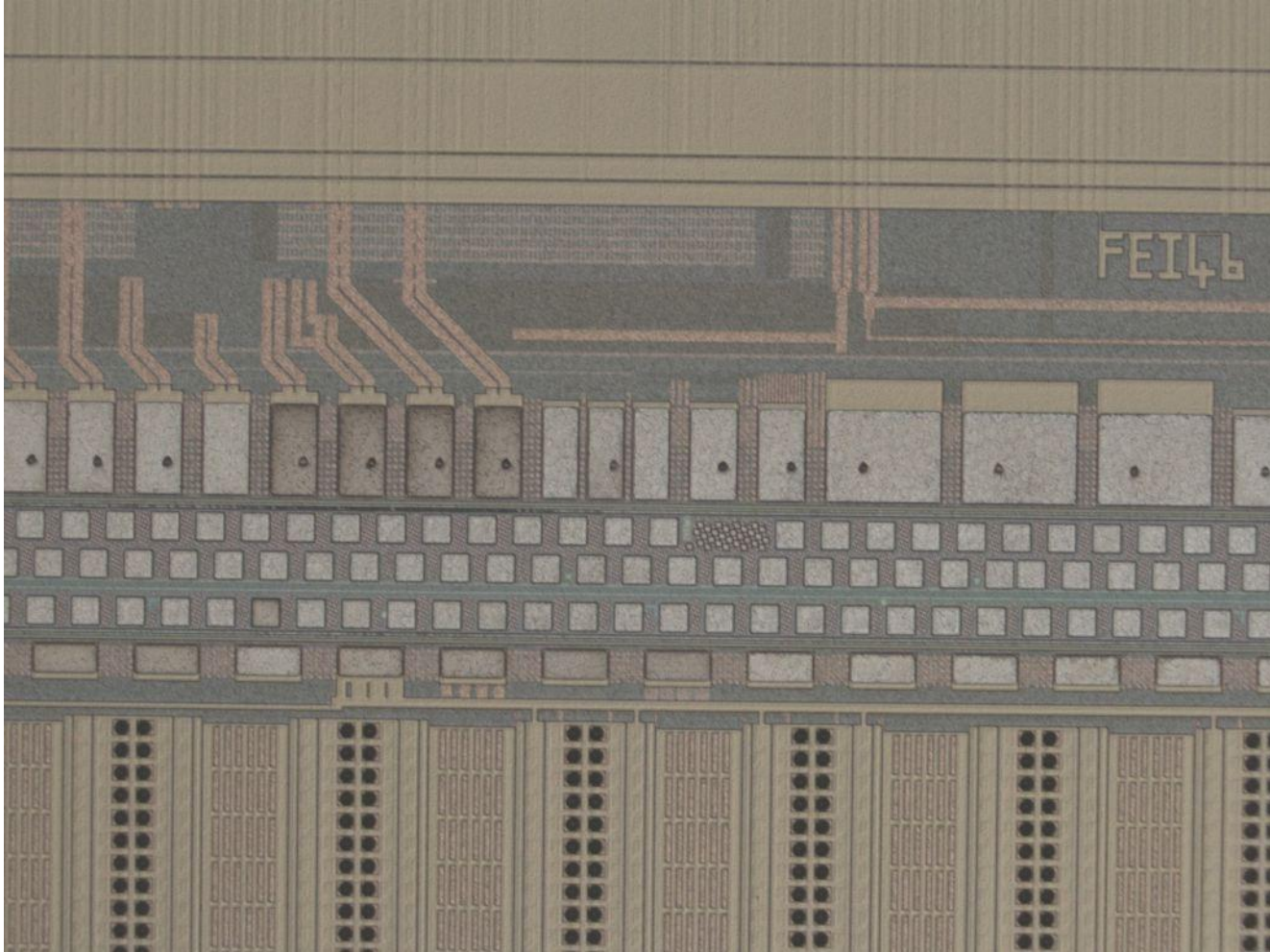
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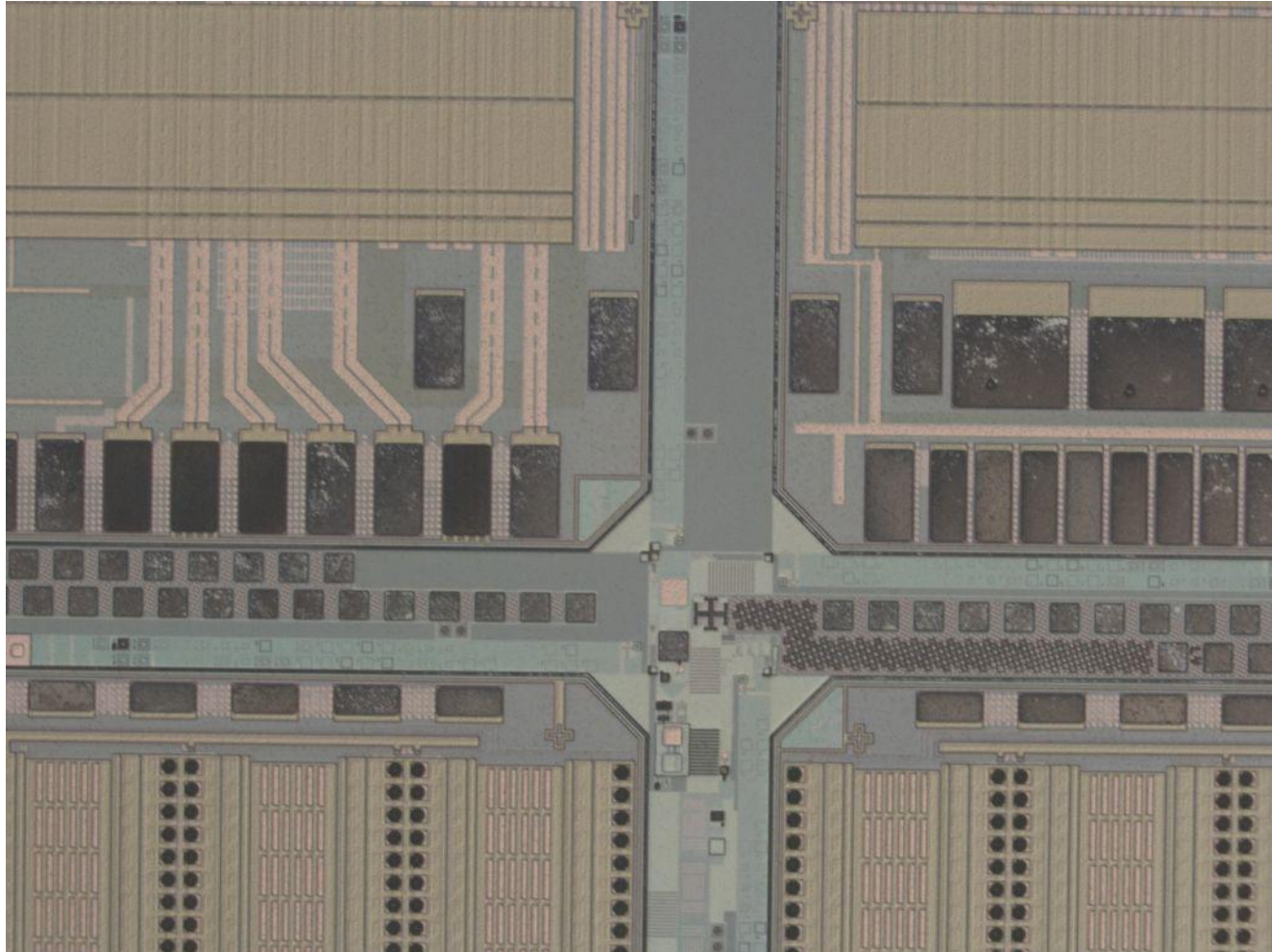
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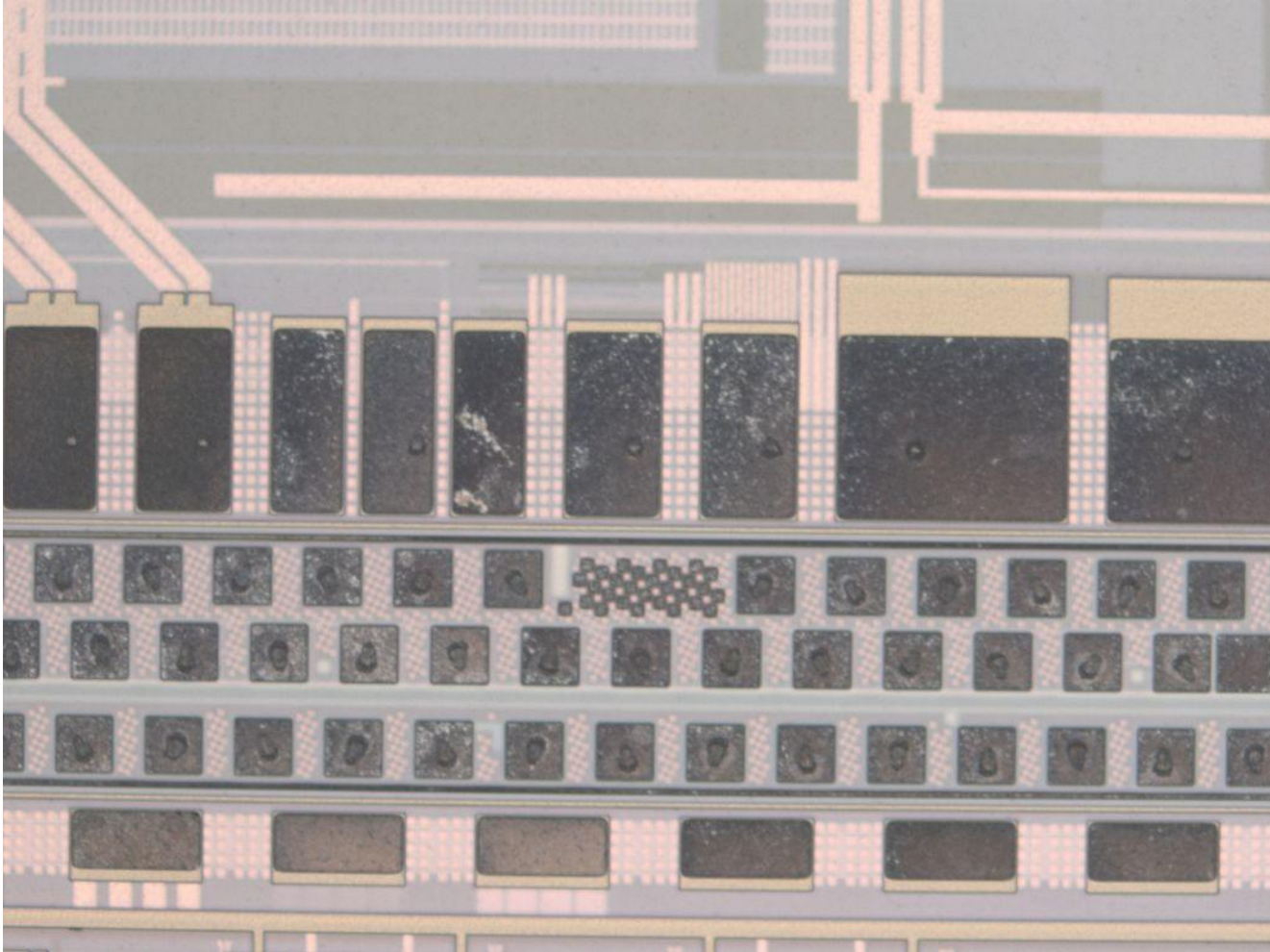
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W#WMB8WDH

Best location on wafer at very perimeter

No bumps here anymore

